

What is claimed is:

1. A semiconductor device comprising:

an insulating gate field effect transistor comprising
a plurality of transistor cells which are arranged in a
semiconductor layer and connected in parallel; and

a protective diode connected between a gate and a
source of said insulating gate field effect transistor to
break down an input of a constant voltage or more applied
between said gate and said source,

wherein said protective diode is formed as a
bidirectional diode in which one or more ring-shaped p-
type layers and one or more ring-shaped n-type layers are
flatly and alternately provided on an insulating layer at
a peripheral portion than said transistor cells, metal films
in ring-shaped contacting with the most inner layer and the
most outer layer of said p-type layers or said n-type layers
are formed respectively, and each of said metal films is
successively formed with either of a source wiring or a gate
electrode pad consisting of a metal film, respectively.

2. The semiconductor device of claim 1, wherein one
ring-shaped metal film of said metal films provided so as
to contact with said the most outer layer is a gate wiring
successively formed with said gate electrode pad, and the
other metal film of said metal films provided so as to
contact with said most inner layer is said source wiring.

3. The semiconductor device of claim 2, wherein said
one ring-shaped metal film is a gate wiring which has gate

connecting portions so as to connect to gate electrodes of
said transistor cells with partial striding over said
protective diode, and said gate connecting portions and
source connecting portions of said source wiring which are
5 contacted with said most inner layer are alternately formed
in plan view.

4. The semiconductor device of claims 1, 2 or 3,
wherein said p-type layers and said n-type layers are made
of at least one selected from polysilicon, amorphous silicon,
10 single-crystal silicon on a insulating layer, SiC and SiGe.

5. The semiconductor device of any one of claims 1
to 4, wherein said p-type layers and said n-type layers are
formed so as to have the same width and the same
concentration of impurities, in the same conductivity type,
15 respectively.

6. The semiconductor device of any one of claims 1
to 5, wherein a diffusion region having a difference
conductivity type from that of said semiconductor layer is
formed on the closest side to said protective diode of said
20 transistor cells arranged, and said source wiring contacted
to the most inner layer of said protective diode is contacted
to said diffusion region.

7. A semiconductor device according to claim 1,
wherein said p-type layers and said n-type layers comprising
25 said bidirectional diode are not flatly formed but are
alternately formed in a height direction.